NOTES

1. MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203 ± 0.008
BODY: SEMICONDUCTOR MOLDING BODYS, CONTACT QPTECHNOLOGIES FOR DETAILS.

2. FINISH:
LEAD FRAME: ELECTROLESS NICKEL. MIL-C-26074, CLASS 1,
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220